



PART NO. : TG10-DA1NSLF

6PIN SMT ISOLATION MODULE

DESIGNED FOR CIRRUS LOGIC DIGITAL AUDIO
INTERFACE APPLICATIONS

LEAD-FREE/RoHS COMPLIANT

COMPATIBLE TO LEAD-FREE SOLDERING PROCESS
CONDITION PER IPC/JEDEC J-STD-020C

UL/EN60950 AND DEMKO RECOGNIZED

EXTENDED OPERATING TEMPERATURE $-40/+85^{\circ}\text{C}$

ELECTRICAL SPECIFICATIONS @25°C

URNS RATIO

P1-2:P6-5

1:1 $\pm 2\%$

OCL (100KHz,0.1V)

P1-2

750 μH nom

DCR P1-2

0.5 Ω max

LL P1-2

1.0 μH max

Cw/w P1-6

(Ground P3)

18pF max

9pF max

BANDWIDTH (Nominal)

10kHz-200MHz

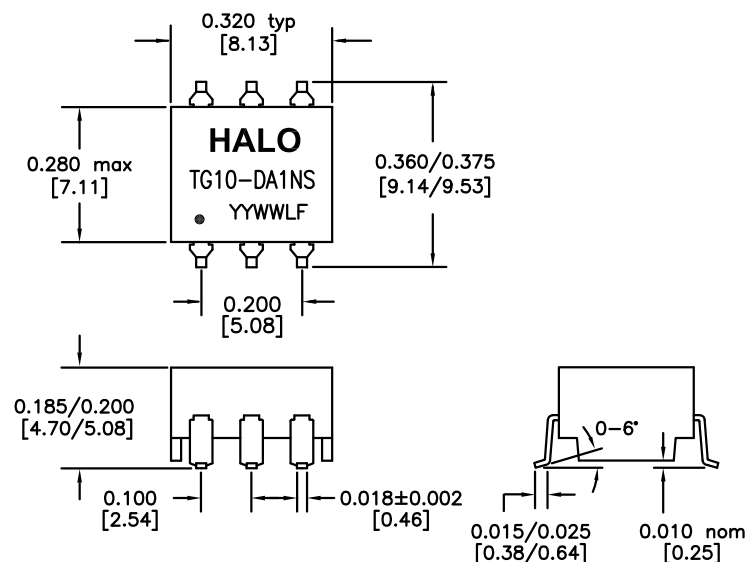
ISOLATION

PRI - SEC

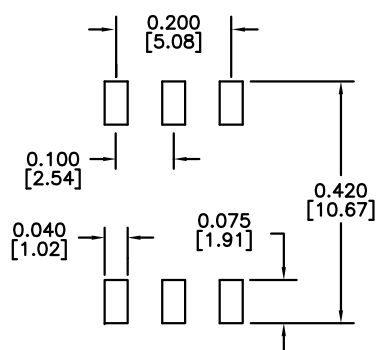
1500Vrms

PRI,SEC - SHIELD

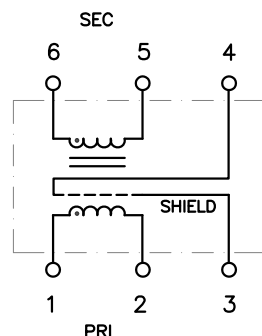
1500Vrms



DIMENSIONS: Inch [mm]
CO-PLANARITY: 0.004 [0.10]
TOLERANCES: ± 0.005 INCH IF NOT SPECIFIED



RECOMMENDED SOLDER PAD DIMENSIONS



ONLY ONE END OF THE
SHIELD CAN BE GROUNDED

HALO/PBL

CALIFORNIA, USA
KOWLOON, HONG KONG
SINGAPORE

TITLE	ISOLATION MODULE	SIGNATURES	DATE	REV.	DESC.	DATE
FOR	CIRRUS LOGIC DIGITAL AUDIO	DRAWN LI ZHI ZHONG	5/4/16	A	PROD. RELEASE	5/4/16
PART NO.	TG10-DA1NSLF	CHECKED LEI KEONG	8/8/16	B	ADD BW SPEC.	5/13/16
SCALE	NONE	APPROVED PETER LU	8/8/16	C	UPDATE	5/17/16
PAGE	1 OF 1	FILE DA1NSLF.DWG		D	UPDATE DESC.	8/8/16

